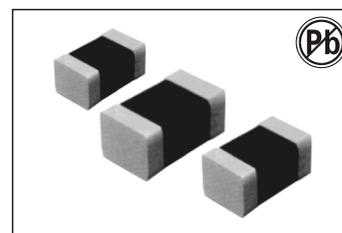


SURFACE-MOUNT MULTI-LAYER CHIP BEADS FASBL 2012,3216 SERIES



FEATURES:

- Multilayer structure
- Closed magnetic circuit
- Avoids crosstalk
- Excellent magnetic shield
- Excellent solderability
- High reliability
- EMI/RFI suppression
- 20% impedance tolerance

OPTIONS:

- Packaging: Tape & Reel is standard (Qty's: 2000 pcs)
- Bulk packaging available for smaller quantities
- Impedance: Optional values available

COMMON APPLICATIONS:

- Cellular Phones
- Mobil Radios
- Cordless Telephones
- Modems
- Global Positioning Systems
- Wireless Communications Equipment
- Network Systems
- Computer Products

ELECTRICAL CHARACTERISTICS

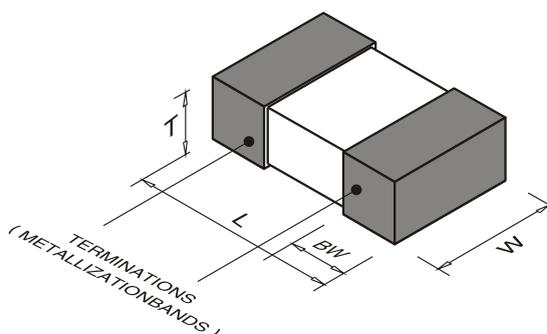
Part Number	IMPEDANCE AT 100 MHz	DCR () Max	IDC Max mA	Part Number	IMPEDANCE () AT 100 MHz	DCR () Max	IDC Max mA
FASBL2012A070H	7	0.20	600	FASBL3216A700H	70	0.30	400
FASBL2012A110H	11	0.20	600	FASBL3216A800H	80	0.30	300
FASBL2012A190H	19	0.20	600	FASBL3216A101H	100	0.30	300
FASBL2012A260H	26	0.20	400	FASBL3216A121H	120	0.30	300
FASBL2012A310H	31	0.20	400	FASBL3216A151H	150	0.30	300
FASBL2012A360H	36	0.20	400	FASBL3216A181H	180	0.35	300
FASBL2012A600L	60	0.25	400	FASBL3216A221H	220	0.30	300
FASBL2012A700L	70	0.25	400	FASBL3216A301H	300	0.30	300
FASBL2012A800L	80	0.25	400	FASBL3216A501H	500	0.30	200
FASBL2012A101L	100	0.25	400	FASBL3216A601H	600	0.30	200
FASBL2012A121L	120	0.25	300	FASBL3216A801H	800	0.30	200
FASBL2012A151L	150	0.25	300	FASBL3216A102H	1000	0.30	200
FASBL2012A181L	180	0.25	300	FASBL3216A122H	1200	0.50	100
FASBL2012A221H	220	0.25	300	FASBL3216A152H	1500	0.60	100
FASBL2012A301H	300	0.25	300	FASBL3216A202L	2000	0.60	100
FASBL2012A501H	500	0.35	200	FASBL3216A252L	2500	0.80	100
FASBL2012A601H	600	0.40	200	FASBL3216A302L	3000	1.00	80
FASBL2012A801H	800	0.40	150				
FASBL2012A102H	1000	0.45	100				
FASBL2012A122H	1200	0.06	100				
FASBL2012A152H	1500	0.80	100				
FASBL2012A202H	2000	0.90	50				
FASBL2012A222H	2200	1.00	50				
FASBL2012A252H	2500	1.20	50				
FASBL2012A302H	3000	1.40	50				
FASBL3216A190H	19	0.20	500				
FASBL3216A260H	26	0.20	500				
FASBL3216A310H	31	0.30	500				
FASBL3210A600H	60	0.30	400				

Note: 1. K= 10%, M= 20%

TECHNICAL INFORMATION PHYSICAL CHARACTERISTICS

Testing: Impedance vs. Frequency: HP 4195A
 Solderability: 90% of the terminal electrode shall be covered
 Preheat: @ 260 5 for 60 seconds
 Flux: Rosin, Dip for 10 seconds 1 second
 Thermal Shock: Impedance shall be within 20% of initial value when temperature is -25 and +85 for 30 minutes for each 50 cycles
 Operating Temperature: -25 to +85
 Storage Temperature: -25 to +85

(Refer to Size Chart Page 4)



Note: All specifications subject to change without notice.